

Final Product/Process Change Notification Document #:FPCN24132ZD Issue Date:02 Dec 2021

Title of Change:	Transfer assembly from KINGPAK To Tong Hsing Electronic Industries for AR0132AT6B00XPD20		
Proposed Changed Material First Ship Date:	01 Apr 2022 or earlier if approved by customer		
Current Material Last Order Date:	31 Dec 2021 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.		
Current Material Last Delivery Date:	31 Mar 2022 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory		
Product Category:	Active components – Integrated circuits		
Contact information:	Contact your local onsemi Sales Office or Mike.Webster@onsemi.com		
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order or < <u>PCN.samples@onsemi.com</u> >. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Sample Availability Date:	31 Jan 2022		
PPAP Availability Date:	31 Jan 2022		
Additional Reliability Data:	Contact your local onsemi Sales Office or <u>Amy.Wu@onsemi.com</u>		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact <u>PCN.Support@onsemi.com</u> .		
Change Category			
Category	Type of Change		
Process - Assembly	Move of all or part of assembly to a different location/site/subcontractor.		

Description and Purpose:

onsemi is relocating AR0132-based family of products for die reconstruct assembly from Kingpak, Chung Lee, Taiwan to Tong Hsing Electronics Limited (THELT), Longtan, Taiwan. Kingpak is a wholly owned subsidiary of Tong Hsing. The existing Kingpak facility will stop RECON production as of 12/31/21.

The AEC-100 qualification of the AR0132 product family is not completed yet, but the qualification for the same new site passed on other similar product families. We expect to complete AEC qualification on the AR0132 in January 2022 and will notify customers with this data once available, along with all supporting data.

	Before Change Description	After Change Description
Reconstruct Assembly Site	Kingpak	Tong Hsing Electronic Industries

There are no product material changes as a result of this change.

There is no product marking change as a result of this change.



Reason / Motivation for Change:	Source/Supply/Capacity Changes				
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	product performed by onsemi in relation to the PCN, associated risks are verified and excluded.				
	No anticipated impacts.				
Sites Affected:					
onsemi Sites		External Foundry/Subcon Sites			
None		Kingpak, Taiwan			
		Tong Hsing Electroni	c Industries, Ltd. , Taiwan		
Marking of Parts/ Traceability of Change:	Date Code				
Reliability Data Summary:					
AEC-Q100 data will be made available o time to review the change. Reliability q	•	o ,	via PCN ahead of this conversion to provide adequate		
Electrical Characteristics Summary	:				
Electrical characteristics are not impact	ed.				
List of Affected Parts:					
			arts affected by this PCN are shown in the customer		
Note: Only the standard (off the shelf) p	il notification, or on the <u>PCN</u>		arts affected by this PCN are shown in the customer Qualification Vehicle		